

ABSTRACT OF DISCLOSURE

MULTILAYER CIRCUIT BOARD AND METHOD FOR MANUFACTURING
MULTILAYER CIRCUIT BOARD

A multilayer circuit board that has electrodes only on one surface is manufactured as follows. A plurality of conductor layers are formed on a resin film made of thermoplastic resin to form a single-sided conductor layer film. Then, a plurality of via-holes 24, which are bottomed by the conductor layers, are formed in the resin film. Then interlayer connecting material is packed in the via-holes 24 to form a single-sided conductor layer film having the interlayer connecting material. A plurality of single-sided conductor layer films are formed and stacked such that surfaces having the conductor layers face in the same direction. Then, the single-sided conductor layer films are pressed and heated to complete the multilayer circuit board. The multilayer circuit board is formed by using only the single-sided conductor layer films and pressing once, so the manufacturing process is simplified.



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